

## FPM-Trinity

~ Innovation for future PCB manufacturing ~



### Digital printing + SMT

- Minimum waste
- 3D free shape electronics
- Rapid manufacturing

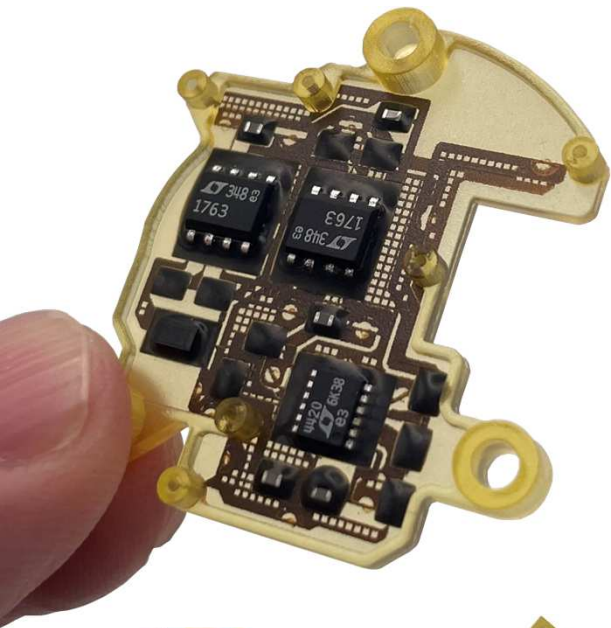


### Direct Resin Printing

### Direct Conductive Printing

### Low temperature SMT

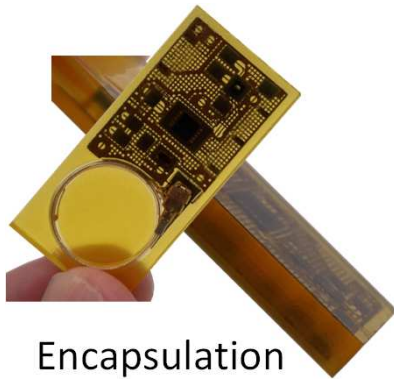




## Shape Your Ideas !



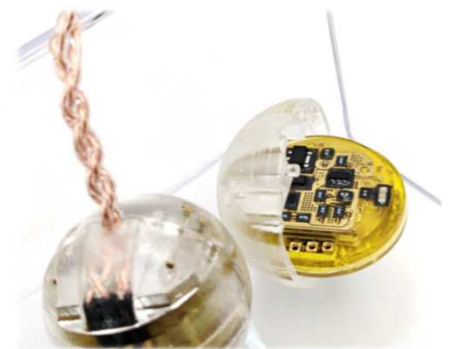
3D module



Encapsulation



Rapid PoC



Easy assembling

## Specification of sample manufacturing service

	Parameter	Design rule
Circuit formation	Conductive material	Silver ink
	Standard thickness	4 or 7 um
	Min. L/S	140 / 200 um
Resin formation	Max resin build size	120 x 60 mm
	Max resin build thickness	4 mm
	Size of print bed	120 x 120 mm
Layer to layer connection	Max layer count	5 layers
	L to L connection	Blind via hole
Part mounting	Conductive material	Silver paste
	Min. electrode pitch (Peripheral)	0.5 mm
	Min. part size	0.6 x 0.3 mm